

ON Semiconductor		6/5/2021		
基础器件	74LCX125	无卤素(HF)	无铅(Pb-free)	
供订购的器件	74LCX125M	总重量(mg)	155.905	
单一材料	重量 (mg)	材料物质成分	CAS #	占平均重量的 %
裸片	3.63	Silicon (Si)	7440-21-3	100
裸片粘接	0.367	Silver (Ag)	7440-22-4	78.5
		Phenolic Resin-2	54208-63-8	21.5
引线框	68.71	Silver (Ag)	7440-22-4	0.0218309
		Zinc (Zn)	7440-66-6	0.125164
		Iron (Fe)	7439-89-6	2.349
		Copper (Cu)	7440-50-8	97.4225
		Phosphorus (P)	7723-14-0	0.081502
Mold Compound-Black	81.974	邻甲酚醛树脂	29690-82-2	20.0002
		Carbon Black (C)	1333-86-4	1.00032
		Fused Silica (SiO2)	60676-86-0	78.9994
镀层	0.944	Palladium (Pd)	7440-05-3	3.60169
		Nickel (Ni)	7440-02-0	94.3856
		Gold (Au)	7440-57-5	2.01271
Wire Bond - Au	0.28	Gold (Au)	7440-57-5	100
<p>材料公开免责声明： Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels of dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of RoHS restricted substances. Lead (Pb) and lead oxide (PbO) are exempted with the RoHS exemption 7(a), 7(c) and 15. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>https://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>				